MAPT Packaging Outline:

- As a 'thank you' to the MAPT Chapter 7 Packaging contributors you're invited to review white papers to our MAPT Packaging program solicitation.

- If you're interested in a project, you may sponsor it and get access to that project, and every other project selected by your co-authors potentially up to 16 projects, for the price of sponsoring your 1 project.

Dave will talk further about the opportunity

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Elite Contributors

Contributors may sign up to review solicitation concept papers.

If interested in any, recommend it/them for full proposals.

Select one or more full proposals to sponsor.

Contributors

Griselda Bonilla (IBM) – *Chair*

Henning Braunisch (Intel) – *Vice Chair*

Ganesh Subbarayan (Purdue University) – *Vice Chair*

Amit Agrawal (NIST)

Bilal Akin (UT- Dallas)

David Bergman (IPC)

Kirk Bresniker (Hewlett Packard Enterprise)

Yu (Kevin) Cao (Arizona State University)

Abjhit Chatterjee (Georgia Tech)

Aiping Chen (LANL)

Gary Chen (TSMC)

Promod Chowdhury (IBM)

Bob Conner (3D Glass Solutions)

Josh Conway (America's Frontier Fund)

Mike Delaus (Analog Devices)

Patrice Ducharme (IBM)

Jeb Flemming (3D Glass Solutions)

John T. Heron (University of Michigan)

Tengfei Jiang (University of Central Florida)

Dan Jiao (Purdue University)

Dae Young Jung (SUNY Binghamton)

Pikyu Kang (Samsung)

Zia Karim (Yield Engineering Systems)

Jason Kawasaki (UW-Madison)

Matt Kelly (IPC)

Jong-Hoon Kim (SK hynix)

Walter Kocon (GlobalFoundries)

Michel Koopmans (Micron)

Deepak Kulkarni (AMD)

Gilles Lamant (Cadence)

David Landsman (Western Digital)

Thomas LeBrun (NIST)

Timothy Lee (Boeing)

Heejin Lee (SK hynix)

Sung-Kyu Lim (Georgia Tech)

Ravi Mahajan (Intel)

Babu Mandava (3D Glass Solutions)

Varughese Mathew (NXP)

Andrew Mawer (NXP)

Rajiv Mongia (Intel)

Benoit Montreuil (Georgia Tech)

Kwangjin Moon (Samsung)

John Oakley (SRC)

Valérie Oberson (IBM)

Kunal R. Parekh (Micron)

John Park (Cadence)

Mark Poliks (SUNY Binghamton)

Kaladhar Radhakrishnan (Intel)

Gnyaneshwar Ramakrishna (Cisco)

Urmi Ray (iNEMI)

Sathya Raghavan (IBM)

Sadasivan Shankar (SLAC Nat'l Lab)

Ravi Shenoy (Qualcomm)

Akshay Singh (Micron)

Suresh Sitaraman (Georgia Tech)

Spyridon Skordas (IBM)

Ilseok Son (TEL)

Eric Tervo (UW-Madison)

Sharad Vidyarthy (Analog Devices)

Chip White (Georgia Tech)

Glen Wilk (ASM)

Brett Wilkerson (AMD)

Jaimal Williamson (Texas Instruments)

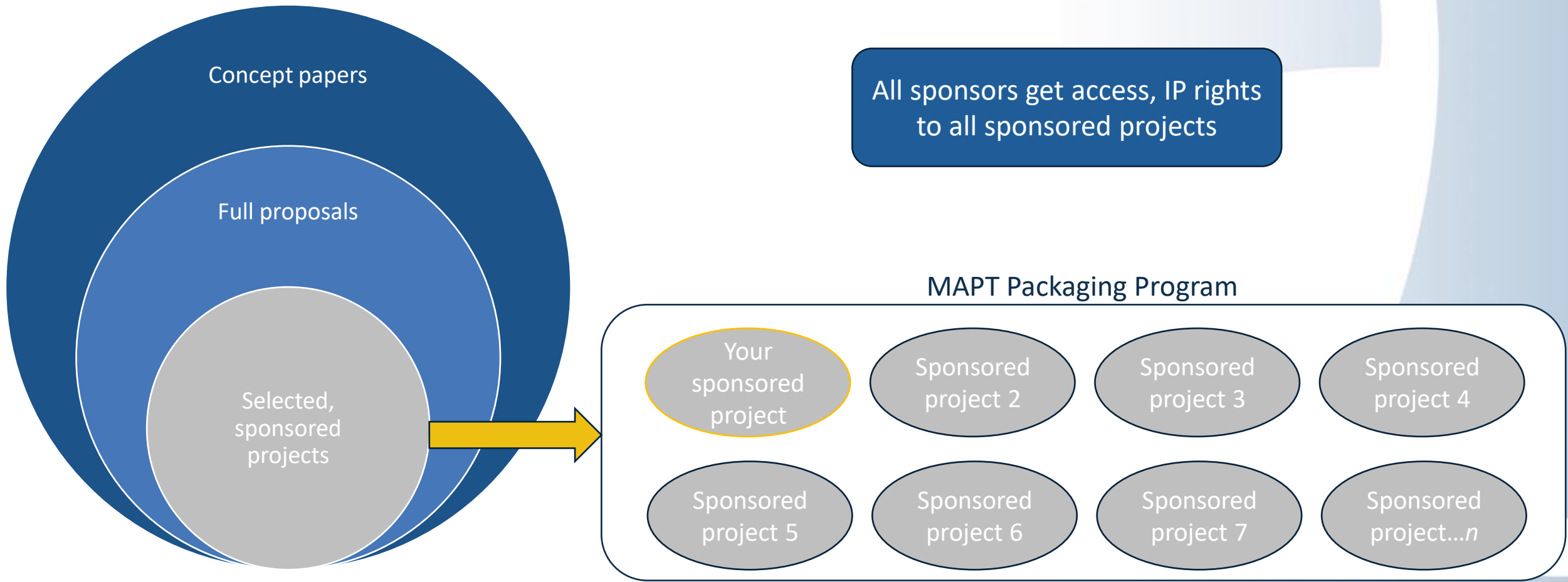Charles G. Woychik (Skywater Technologies)

Jinkyoung Yoo (LANL)

SeHo You (Samsung)

Katie C. Yu (NXP)

Ming Zhang (PDF Solutions)

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MAPT Chapter 7 Packaging contributors each sponsor 1 project
Leads to 10- 16 projects in the program

Concept papers

Full proposals

Selected, sponsored projects

All sponsors get access, IP rights to all sponsored projects

MAPT Packaging Program

Your sponsored project

Sponsored project 2

Sponsored project 3

Sponsored project 4

Sponsored project 5

Sponsored project 6

Sponsored project 7
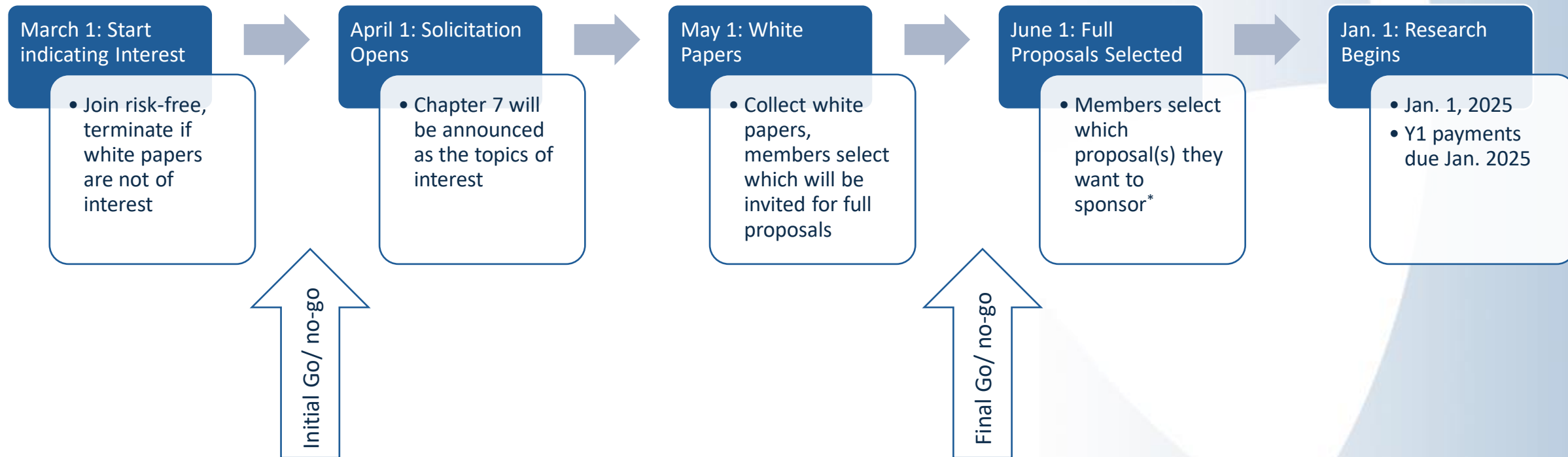
Sponsored project...*n*

Pay/ Get

What you pay:

- Sponsor 1 research project for $105K/yr. for 3 years
- $15K annual membership fee

What you get:

1. Project sponsorship: Direct conversations with the faculty and students performing the research on your selected sponsored projects plus at least 9 other sponsored projects in this program. Including exclusive and early access to research results.

   - Ability to steer, and guide the research while extracting real-time experimental results
   - Consultations with the researchers for ideation, thought generation, results interpretation, and expert advising of next steps
   - Collaborative paper and patent writing
   - Consideration of graduate students working on these projects for internships, full-time hires

2. Membership fee covers

   - Online account access for all employees at your company
   - IP rights to all projects within the program
   - Free, unlimited attendance at Program Annual Review
   - All legal contracts with researchers, members, IP, confidentiality
   - Access to SRC student scholars database of ~1,400 active student researchers sponsored by SRC
   - Professional management of program

3. Risk free: cancel after reviewing concept papers, no obligation

   - If you choose to sponsor, no payments due until 2025

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When & How This Will Happen

March 1: Start indicating Interest
- Join risk-free, terminate if white papers are not of interest

April 1: Solicitation Opens
- Chapter 7 will be announced as the topics of interest

May 1: White Papers
- Collect white papers, members select which will be invited for full proposals

June 1: Full Proposals Selected
- Members select which proposal(s) they want to sponsor*

Jan. 1: Research Begins
- Jan. 1, 2025
- Y1 payments due Jan. 2025

Initial Go/ no-go

Final Go/ no-go

Risk-free: Members can resign and terminate commitment, with no cost at either Go/No-Go
- Initial Go/ no-go: 12 participants agree to sponsor at least 1 project each
- Final Go/ no-go: Commitments of at least 10 projects are needed to proceed

No membership dues until 2025

Next Steps

- Contact David.Henshall@src.org to request a membership agreement
  - Should be ready within about a week
- Sign and return membership agreement by May 1
- Review white papers
- Chose to remain in the program or terminate with no obligation
- If remaining, choose Full Proposal to sponsor